## Tender of 20-year Government Bonds under Institutional Bond Issuance Programme to be held on May 25

The following is issued on behalf of the Hong Kong Monetary Authority:

The Hong Kong Monetary Authority (HKMA), as representative of the Hong Kong Special Administrative Region Government (HKSAR Government), announced today (May 16) that a tender of 20-year Government Bonds (Bonds) under the Institutional Bond Issuance Programme will be held on May 25 (Wednesday), for settlement on May 26 (Thursday).

A total of HK\$0.5 billion 20-year Bonds will be tendered. The Bonds will mature on May 26, 2042 and will carry interest at the rate of 3.30 per cent per annum payable semi-annually in arrears.

Under the Institutional Bond Issuance Programme, tender is open only to Recognized Dealers which are appointed as Primary Dealers. Anyone wishing to apply for the Bonds on offer can do so through any of the Primary Dealers on the current published list, which can be obtained from the Government Bond Programme's website at <a href="https://www.hkgb.gov.hk">www.hkgb.gov.hk</a>. Each tender must be for an amount of HK\$50,000 or integral multiples thereof.

Tender results will be published on the HKMA's website, the Government Bond Programme's website, the Refinitiv screen (HKGBINDEX), and Bloomberg (GBHK <GO>) not later than 3pm on the tender day.

HKSAR Government Institutional Bond Issuance Programme tender information

Tender information of 20-year Government Bonds under the Institutional Bond Issuance Programme:

Issue Number : 20GB4205

Stock Code : 4255 (HKGB 3.30 4205)

: May 25, 2022 (Wednesday) Tender Date and Time

9.30am to 10.30am

Issue and Settlement

Date for Tender Amount : May 26, 2022 (Thursday)

Amount on Offer : HK\$0.5 billion

: 20 years Maturity Maturity Date : May 26, 2042

: 3.30% p.a. payable semi-annually in arrears Interest Rate

November 28, 2022 May 29, 2023 November 27, 2023 May 27, 2024 November 26, 2024 May 26, 2025 November 26, 2025 May 26, 2026 November 26, 2026 May 26, 2027 November 26, 2027 May 26, 2028 November 27, 2028 May 28, 2029 November 26, 2029 May 27, 2030 November 26, 2030 May 26, 2031 November 26, 2031 May 26, 2032 Interest Payment Dates November 26, 2032 May 26, 2033 November 28, 2033 May 26, 2034 November 27, 2034 May 28, 2035 November 26, 2035 May 26, 2036 November 26, 2036 May 26, 2037 November 26, 2037 May 26, 2038 November 26, 2038 May 26, 2039 November 28, 2039 May 28, 2040 November 26, 2040 May 27, 2041 November 26, 2041 May 26, 2042 : Competitive tender Each competitive tender must be for an amount of HK\$50,000 or integral multiples : thereof. Any tender applications for the Bonds must be submitted through a Primary Dealer on the current published list. Please see Information Memorandum available on the Government Bond Programme's website at <a href="https://www.hkgb.gov.hk">www.hkgb.gov.hk</a> or approach Primary Dealers. Expected commencement : May 27, 2022

Method of Tender

Tender Amount

Other Details

date of dealing on

the Stock Exchange of Hong Kong Limited

Yield-to-Maturity	Price	Yield-to-Maturity	Price
2.300	116.19	3.300	100.39
2.350	115.33		99.67
2.400	114.47	3.400	98.96
2.450	113.63	3.450	98.26
2.500	112.79	3.500	97.56
2.550	111.96	3.550	96.87
2.600	111.14	3.600	96.19
2.650	110.32	3.650	95.51
2.700	109.52	3.700	94.84
2.750	108.72	3.750	94.17
2.800	107.93	3.800	93.51
2.850	107.14	3.850	92.86
2.900	106.36	3.900	92.21
2.950	105.59	3.950	91.57
3.000	104.83	4.000	90.93
3.050	104.07	4.050	90.30
3.100	103.32	4.100	89.67
3.150	102.58	4.150	89.05
3.200	101.84	4.200	88.44
3.250	101.11	4.250	87.83
3.300	100.39	4.300	87.23

\*Disclaimer: The information provided here is for reference only. Although extreme care has been taken to ensure that the information provided is accurate and up-to-date, the HKMA does not warrant that all, or any part of, the information provided is accurate in all respects. You are encouraged to conduct your own enquiries to verify any particular piece of information provided on it. The HKMA shall not be liable for any loss or damage suffered as a result of any use or reliance on any of the information provided here.